

P/N: 16ST6148 DATA SHEET

Feature



- Meets all IEEE802.3 and ANSI X3.263 standards including 350uH OCL with 8mA Bias.
- Designed for use with transceivers from AMD KENDIN Semiconductor and Quality Semiconductor.
- IC grade transfer-molded package suitable for reflow soldering temperatures up to 235°C.
- Patented interlock base construction for high reliability.
- Operating temperature range: 0°C to +70°C.
- Storage temperature range: -25°C to +125°C.

Electrical Specifications @ 25°C						
Part Number	Turns Ratio (±5%)		OCL(uH Min) @100KHz/0.1Vrms with 8mA/DC Bias	L.L (uH Max)		HI--POT (Vrms)
	RX	TX		1-2 short 6-7	16-15 short 10-11	
16ST6148	1CT:1CT	1CT:1.414CT	350	0.5	0.8	1500
Continue						
Part Number	Insertion Loss (dB Max)	Return Loss (dB Min)			Cross talk (dB Min)	
	0.3-100 MHz	30MHz	60MHz	80MHz	0.3-60MHz	60-100MHz
16ST6148	-2.0	-18	-12	-11	-45	-35

Schematic

Mechanical

